

TWM03P41M

P-Channel Enhancement MOSFET

Features

Way-on Small Signal MOSFETs

$V_{DS} = -30\text{ V}$, $I_D = -4.1\text{ A}$

$R_{DS(on)} < 60\text{ m}\Omega$ @ $V_{GS} = -10\text{ V}$

$R_{DS(on)} < 85\text{ m}\Omega$ @ $V_{GS} = -4.5\text{ V}$

Trench LV MOSFET Technology

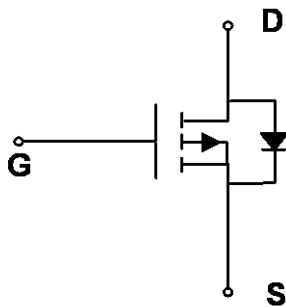
Mechanical Characteristics

SOT-23 Package

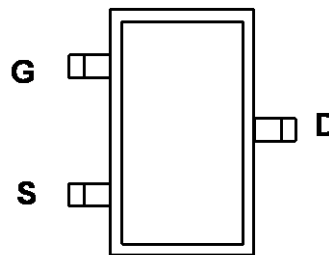
Marking : Making Code

RoHS Compliant

Schematic & PIN Configuration



Device symbol



SOT-23(Top View)

Absolute Maximum Rating ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Units
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	-4.1	A
$T_A=25^\circ\text{C}$			
Pulsed Drain Current ¹	I_{DM}	-16	A
Power Dissipation	P_D	1.2	W
$T_A=25^\circ\text{C}$			
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Units
Thermal Resistance from Junction to Ambient ²	$R_{\theta JA}$	104	$^\circ\text{C/W}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -30V, V _{GS} = 0V	-	-	-1	μA
Gate-Source Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Gate-Source Threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1	-1.5	-2.5	V
Drain-Source on-State Resistance ³	R _{DS(on)}	V _{GS} = -10V, I _D = -4.1A	-	42	60	mΩ
		V _{GS} = -4.5V, I _D = -3A	-	54	85	
Dynamic Characteristics⁴						
Input Capacitance	C _{iss}	V _{GS} = 0V , V _{DS} = -15V, f = 1.0MHz	-	530	-	pF
Output Capacitance	C _{oss}		-	70	-	
Reverse Transfer Capacitance	C _{rss}		-	56	-	
Switching Characteristics⁴						
Total Gate Charge	Q _g	V _{GS} = -10V, V _{DS} = -15V, I _D = -4.1A	-	6.8	-	nC
Gate-Source Charge	Q _{gs}		-	1.0	-	
Gate-Drain Charge	Q _{gd}		-	1.4	-	
Turn-on Delay Time	t _{d(on)}	V _{GS} = -10V, V _{DS} = -15V , R _L = 15Ω,R _{GEN} = 2.5Ω	-	14	-	ns
Rise Time	t _r		-	61	-	
Turn-off Delay time	t _{d(off)}		-	19	-	
Fall Time	t _f		-	10	-	
Source-Drain Body Diode Characteristics						
Diode Forward Voltage ³	V _{SD}	I _S = -4.1A, V _{GS} = 0V	-	-	-1.2	V
Continuous Source Current	I _S		-	-	-4.1	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
2. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse width≤300μs, duty cycle≤2%.
4. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics

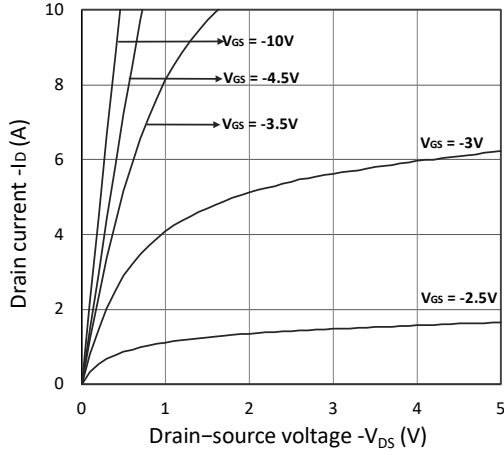


Figure 1. Output Characteristics

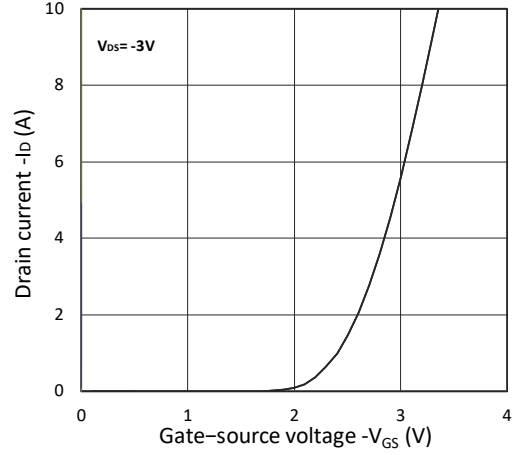


Figure 2. Transfer Characteristics

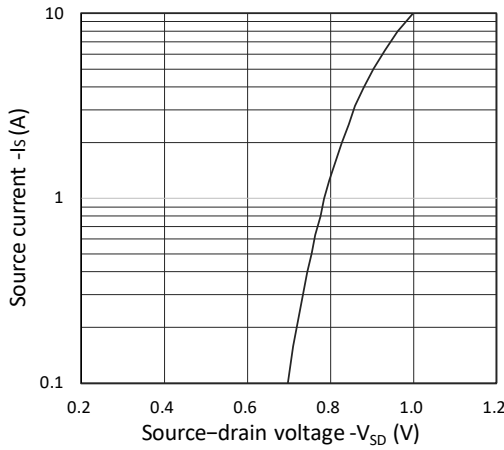


Figure 3. Forward Characteristics of Reverse

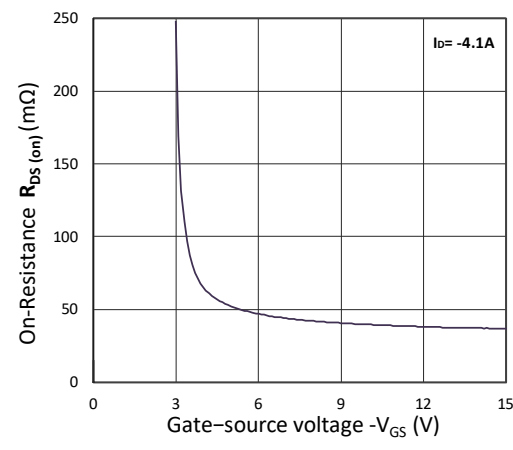


Figure 4. $R_{DS(on)}$ vs. V_{GS}

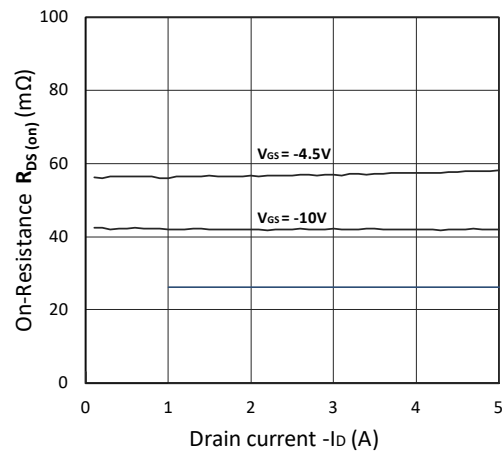


Figure 5. $R_{DS(on)}$ vs. I_D

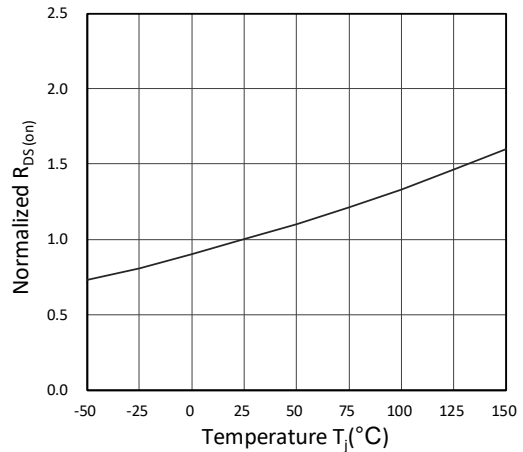


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

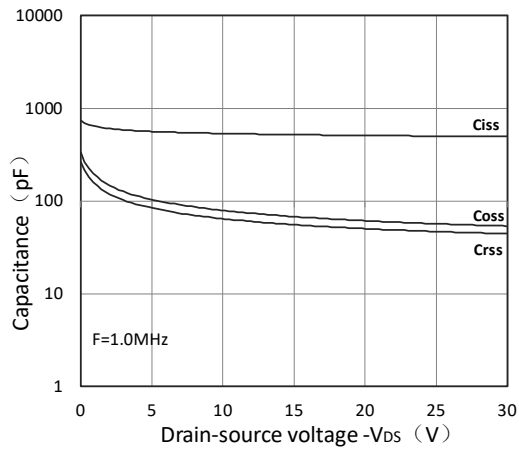


Figure 7. Capacitance Characteristics

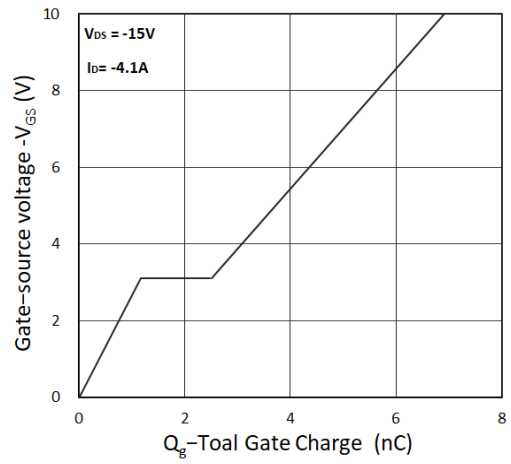
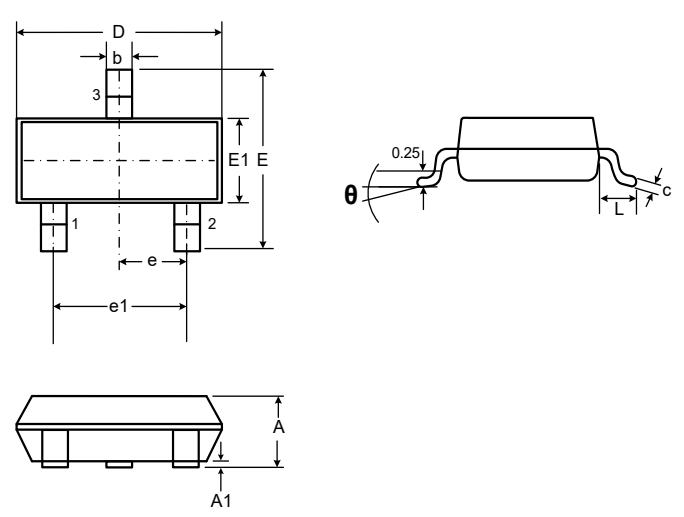
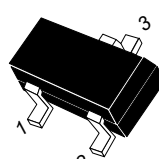


Figure 8. Gate Charge Characteristics

Outline Drawing – SOT-23

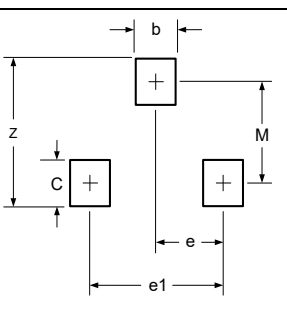
PACKAGE OUTLINE





SOT-23

SYMBOL	MILLIMETER		INCHES	
	MIN	MAX	MIN	MAX
A	0.90	1.15	0.035	0.045
A1	0.00	0.10	0.000	0.004
b	0.30	0.50	0.012	0.020
c	0.08	0.15	0.003	0.006
D	2.80	3.00	0.110	0.118
E	2.25	2.55	0.089	0.100
E1	1.20	1.40	0.047	0.055
e	0.95 BSC		0.037BSC	
e1	1.80	2.00	0.071	0.079
L	0.55REF		0.022REF	
θ	0°	8°	0°	8°

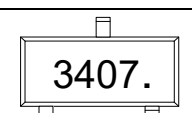


DIMENSIONS		
DIM	INCHES	MILLIMETERS
M	0.080	2.02
C	0.032	0.80
Z	0.111	2.82
e	0.037 BSC	0.95 BSC
e1	0.075 BSC	1.90 BSC
b	0.032	0.80

Notes

1. Dimensioning and tolerances per ANSI Y14.5M, 1985.
2. Controlling Dimension: Inches
3. Pin 3 is the cathode (Unidirectional Only).
4. Dimensions are exclusive of mold flash and metal burrs.

Marking Codes

Part Number	WM03P41M
Marking Code	

Package Information

Qty: 3k/Reel